

Appl. No. 10/757,202
Reply to Office Action of September 1, 2005

Attorney Docket No. 2002-0350 /24061.484
Customer No. 42717

Amendments to the Specification

Please replace the paragraph at lines 5-7 on page 2 with the following amended paragraph:

U.S. Patent No. ~~6,261,258~~ 6,261,158 (Holland et al) describes a two step CMP process for planarizing metal interconnects with the imposition of a cleansing/neutralization step as intermediate between stages of CMP.